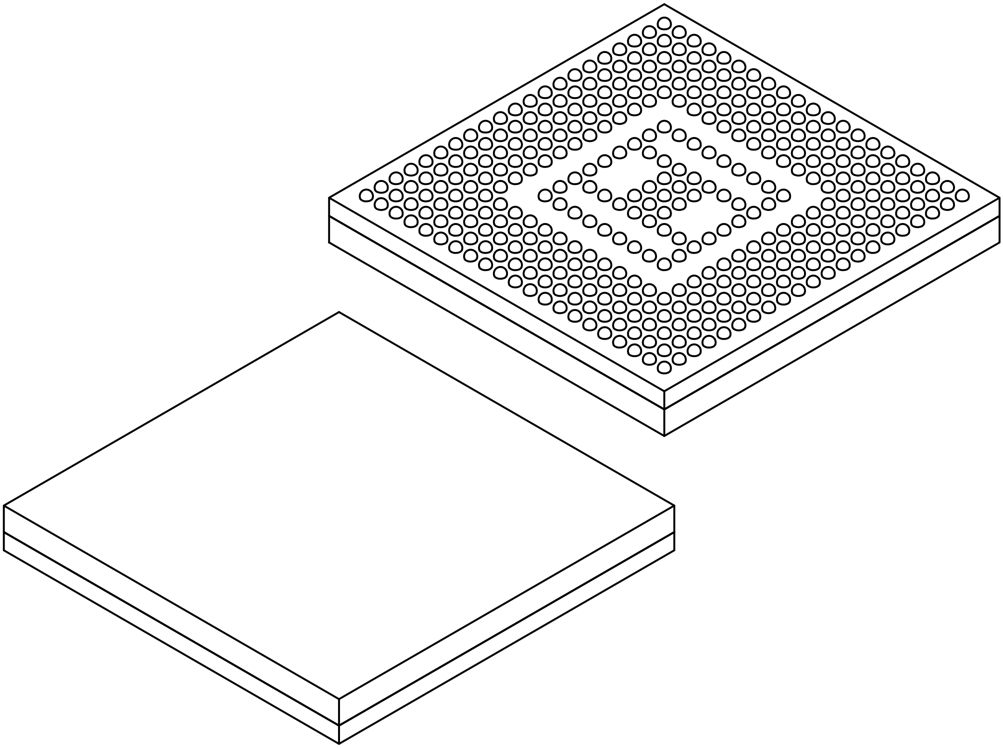
375-Ball Thin Fine-Pitch Ball Grid Array Package (7EW) - 9x9x1.2 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		375	
Pitch	e		0.40 BSC	
Overall Height	A	–	–	1.20
Ball Height	A1	0.11	0.16	0.21
Mold Thickness	M		0.53 REF	
Substrate Thickness	S		0.35 REF	
Overall Length	D		9.00 BSC	
Ball Array Length	D2		8.00 BSC	
Overall Width	E		9.00 BSC	
Ball Array Width	E2		8.00 BSC	
Ball Diameter	b	0.20	0.25	0.30

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.